

## SPECIFICATION FOR LCD MODULE MODULE NO: YB-TG240320S27A-N-B0

## Doc.Version:01

Customer Approval:	
□ Accept	🗌 Reject

YEEBO	NAME	SIGNATURE	DATE
Prepare	Electronic Engineer	項國展	2018/04/23
Check	Mechanical Engineer	林丽苍	2018/04/23
Verify		20 TO	2018/4/23
Approval		康高信	2018/4/23

APPROVAL FOR SPECIFICATIONS ONLY

APPROVAL FOR SPECIFICATIONS AND SAMPLE

WIMRD005-02-D



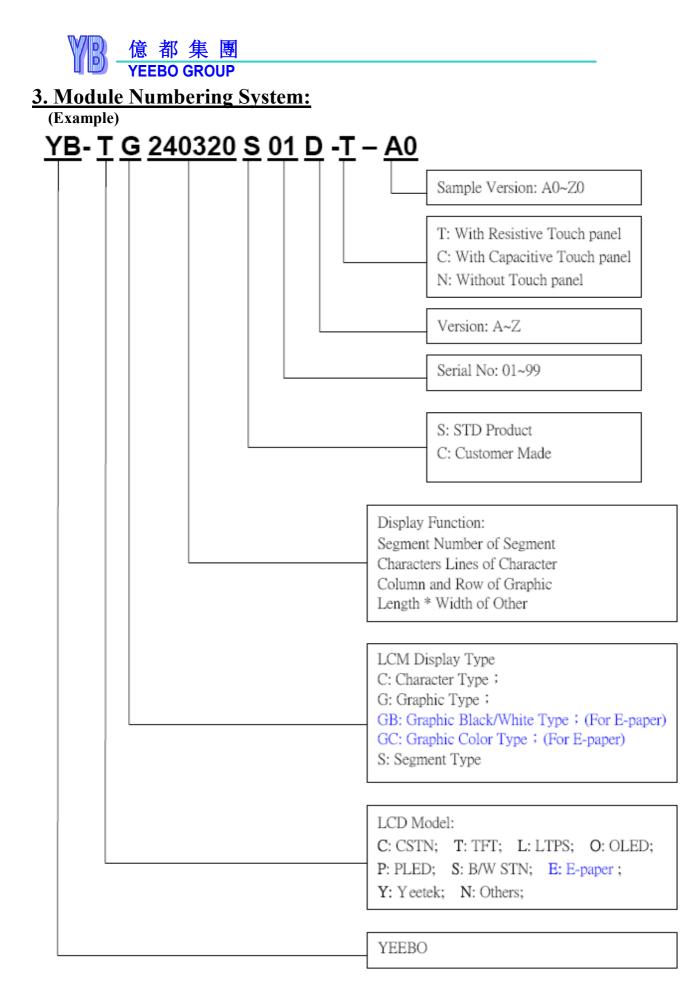
## **<u>1. Revision History</u>**

Sample Version	DOC. Version	DATE		DESCRIPTION	CHANGED BY
B0	00	2017-03-10	SPEC ONLY	First issue	Gavin / Fen
B0	01	2018-04-23	FULL SPEC	First Sample	Gavin / Fen



## **<u>2. Table of Contents:</u>**

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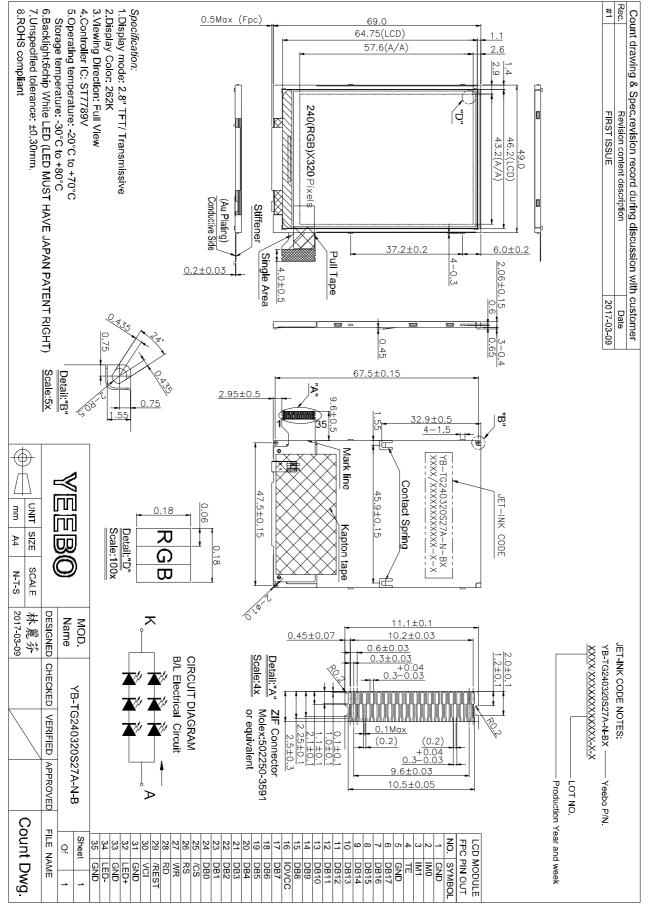
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## 4. General Specification:

ITEM	CONTENTS		
Module Size	49.0 (W) * 69.0 (H) * 2.06 (T) mm		
Module Size(With FPC)	58.6 (W) * 69.0 (H) * 2.06 (T) mm		
Display Size(Diagonal)	2.8 inch		
Display Format	240(RGB)*320 Pixels		
Active Area	43.2(W) * 57.6 (H) mm		
Pixel Pitch	0.18* 0.18 mm		
LCD Type	TFT (262K) / Transmissive / Normally Black		
View Direction	Free		
Controller IC	ST7789V		
Weight	13.6g		



## 5. LCM drawing:



Module P/N:YB-TG240320S27A-N-B0 Doc.Version:01



## **6. Electrical Characteristics**

#### 6-1 Absolute Maximum Ratings

	0			(	-	
Item	Symbol	Min.	Туре	Max.	Unit	Remark
Supply Voltage	V <sub>CI</sub>	-0.3	-	+4.6	V	Note1
Supply Voltage(Logic)	IOV <sub>CC</sub>	-0.3		+4.6		Note1
Logic Input Voltage Range	V <sub>IN</sub>	0.5		IOVcc +0.5	V	Note1
Operating Temperature	Topr	-20	-	+70	°C	-
Storage Temperature	Tstg	-30	-	+80	°C	-

Storage TemperatureTstg-30-+80°CNote1: Absolute maximum rating is the limit value beyond which the IC maybe broken.<br/>They do not assure operations.

#### 6-2 Operating Conditions

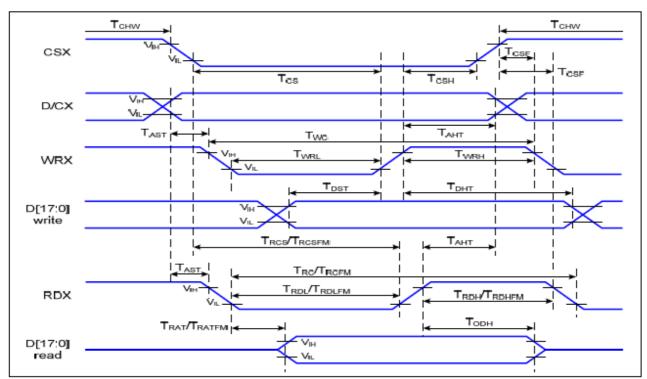
(Ta=25°C)

(Ta=25°C VSS=0V)

Item	Symbol	Condition	Min.	Тур.	Max.	Unit		
Power Supply voltage	V <sub>CI</sub>	-	2.6	2.8	3.3	Volt		
Supply voltage for I/O	IOVcc	-	1.65	2.8	3.3	Volt		
Input Voltago	$\mathrm{V}_{\mathrm{IH}}$	-	0.7 IOVcc	-	IOVcc	V		
Input Voltage	$V_{IL}$	-	V <sub>SS</sub>	-	0.3 IOVcc	V		
Power Supply Current for LCM	Icc	VCI=2.8V	-	9.25	13.8	mA		



6-3 Timing Characteristics 8080 Series MCU Parallel Interface Characteristics: 18/16/9/8-bit Bus



#### Parallel Interface Timing Characteristics (8080-Series MCU Interface)

Signal	Symbol	Parameter	Min	Мах	Unit	Description	
D/CX	T <sub>AST</sub>	Address setup time	0		ns		
DICX	T <sub>AHT</sub>	Address hold time (Write/Read)	10		ns	-	
	T <sub>CHW</sub>	Chip select "H" pulse width	0		ns		
	T <sub>cs</sub>	Chip select setup time (Write)	15		ns		
CSX	T <sub>RCS</sub>	Chip select setup time (Read ID)	45		ns		
CSA	TRCSFM	Chip select setup time (Read FM)	355		ns	-	
	T <sub>CSF</sub>	Chip select wait time (Write/Read)	10		ns		
T <sub>CSH</sub>		Chip select hold time	10		ns		
	T <sub>wc</sub>	Write cycle	66		ns		
WRX	T <sub>WRH</sub>	Control pulse "H" duration	15		ns		
	T <sub>WRL</sub>	Control pulse "L" duration	15		ns		
	T <sub>RC</sub>	Read cycle (ID)	160		ns		
RDX (ID)	T <sub>RDH</sub>	Control pulse "H" duration (ID)	90		ns	When read ID data	
T <sub>RDL</sub>		Control pulse "L" duration (ID)	45		ns		
DDY	T <sub>RCFM</sub> Read cycle (FM)		450		ns	W/h and man and first man	
		Control pulse "H" duration (FM)	90		ns	When read from	
(FM)	M) T <sub>RDLFM</sub> Control pulse "L" duration (FM)		355		ns	frame memory	
D[17:0]	T <sub>DST</sub>	Data setup time	10		ns	For CL=30pF	

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta= -30 to 70  $\,^{\circ}_{\circ}$ 



## 7. Optical Characteristics:

Itore	Item		Conditions	Specifications			II:4	Noto
Item			Conditions	Min	Тур	Max	Unit	Note
Transmittance (With PL)		T(%)	_	-	3.9	-	-	-
Contrast Ratio		CR	⊖=0 Normal Viewing angle	-	800	-		(1)(2)
Response	e time	TR+TF	_	-	30	-	ms	(1) (3)
	Hor	θx+		-	80	-		
Viewing	ПОГ	θx-	CR≧10	-	80	-	deg.	
angle	Ver	θy+		-	80	-	uey.	-
	ver	θy-		-	80	-		

Measuring Condition

- 1. Measuring surrounding: dark room
- 2. Ambient temperature:  $25\pm2^{\circ}$ C
- 3. 30 min. Warm-up time.

Color of CIE Coordinate:

Item		Symbol	Condition	Min.	Тур.	Max.
	D 1	х		0.578	0.628	0.678
	Red	у		0.289	0.339	0.389
	Green	х		0.266	0.316	0.366
Chromaticity Coordinates		у	$\theta=\varphi=0^\circ$	0.556	0.606	0.656
(Transmissive)	Blue	х	LED Backlight	0.092	0.142	0.192
(Transmissive)		у		0.050	0.100	0.150
	<b>XX</b> 71 · 4	Х		0.238	0.288	0.338
	White	у		0.257	0.307	0.357



Note (1) Definition of Viewing Angle :

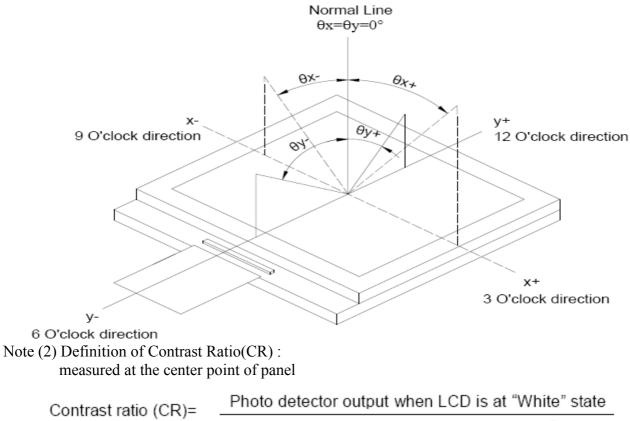
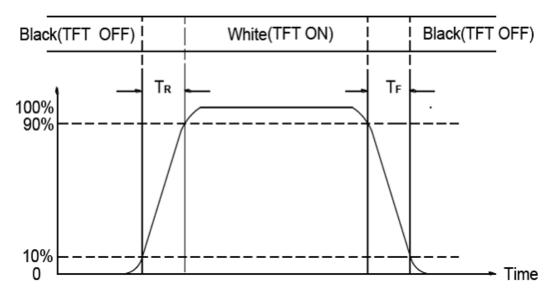


Photo detector output when LCD is at "Black

Note (3) Definition of Response Time : Sum of TR and TF





## 8. Interface Pin Assignment:

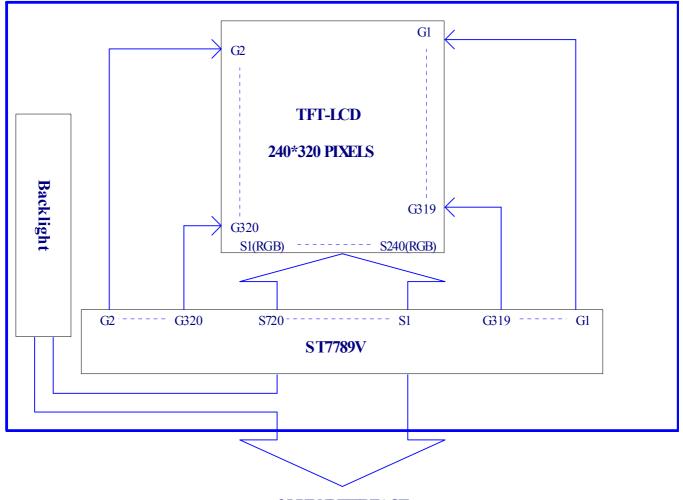
No.	Symbol	Function						
1	GND	Ground	Ground					
		Select MPU In	Select MPU Interface mode					
2	IMO	IM1	IM0	MCU-Interface Mode	DB Pin in use			
		0	0	80 MCU 16-bit bus interface II	D[17:10],D[8:1]			
		0	1	80 MCU 8-bit bus interface II	D[17:10]			
3	IM1	1	0	80 MCU 18-bit bus interface II	D[17:0]			
		1	1	80 MCU 9-bit bus interface II	D[17:9]			
4	TE	Tearing effect	sign	al is used to MCU to fra	ame memory writing			
5	GND	Ground						
6	DB17	Data bus						
7	DB16	Data bus						
8	DB15	Data bus						
9	DB14	Data bus						
10	DB13	Data bus						
11	DB12	Data bus						
12	DB11	Data bus						
13	DB10	Data bus						
14	DB9	Data bus						
15	DB8	Data bus						
16	IOVCC	Digital power s	supp	ly				
17	DB7	Data bus						
18	DB6	Data bus	Data bus					
19	DB5	Data bus						
20	DB4	Data bus						
21	DB3	Data bus						
22	DB2	Data bus						

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23	DB1	Data bus
24	DB0	Data bus
25	/CS	Chip select signal active low
26	RS Display data/command selection pin in parallel interface. Display data(RS=1) / Command selection(RS=0)	
27	WR Write enable in MCU parallel interface	
28	RD	Read enable in MCU parallel interface
29	/RESET	Reset signal active low
30	VCI	Analog power supply
31	GND	Ground
32	LED+	LED power supply(+)
33	GND	Ground
34	LED-	LED power supply(-)
35	GND	Ground



## 9. Block Diagram:



**35 PIN INTERFACE** 



#### **10. Backlight:**

- 1. Standard Lamp Styles (Edge Lighting Type): The LED chips are distributed over the edge light area of the illumination unit, which gives the less power consumption:
- 2. The Main Advantages of the LED Backlight are as following:
  - 2.1 The brightness of the backlight can simply be adjusted. By a resistor or a potentiometer.

3. Data About LED Backlight:	3.	Data	About	LED	Back	light:
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(Ta=25°C)

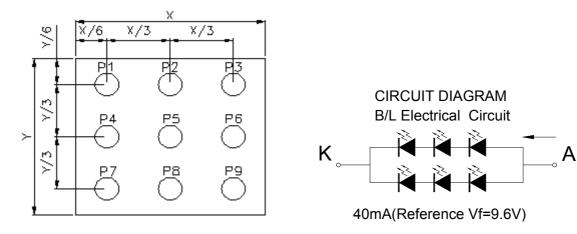
(1w 25 C)							
PARAMETER	Sym.	Min.	Тур.	Max.	Unit	Test Condition	Note
Supply Current	_	-	40	-	mA	V=9.6V	
Supply Voltage	V	8.5	9.6	10.2	V	If=40mA	
Reverse Voltage	VR	-	-	5	V	-	
Luminous Intensity for LCM	IV	280	350	-	Cd/m <sup>2</sup>		2
Uniformity for LCM	-	70	-	-	%	If <b>=40</b> mA	3
Life Time	-	-	50000	-	Hr.		4
Color				Wh	ite		

NOTE:

- 1. Backlight Only
- 2. Average Luminous Intensity of P1-P9
- 3. Uniformity = Min/Max \* 100%
- 4. LED life time defined as follows: The final brightness is at 50% of original brightness

#### Measured Method: (X\*Y: Light Area)

#### **Internal Circuit Diagram**



#### (Effective spatial Distribution)

Hole Diameter ø3 mm; 1 to 9 per Position Measured Luminous



# **<u>11. Standard Specification for Reliability:</u>** 11–1. Standard Specifications for Reliability of LCD Module

No	Item	Description
01	High temperature operation	The sample should be allowed to stand at $70^{\circ}$ C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at $-20^{\circ}$ C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at $80^{\circ}$ C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at $-30^{\circ}$ C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at $60^{\circ}$ C,90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles : -30°C for 30 minutes $\rightarrow$ normal temperature for 5 minutes $\rightarrow$ +80°C for 30 minutes $\rightarrow$ normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range : 10Hz ~ 55Hz Amplitude of vibration : 1.5mm X,Y,Z 2 hours for each direction. Sweep time: 12 min
08	Packing drop test	According to ISTA 1A 2001.
09	Electrical Static Discharge	Air: ±4KV 150pF/330Ω 5 times
	Discharge	Contact: $\pm 2$ KV 150pF/330 $\Omega$ 5 time

\*Sample size for each test item is 3~5pcs



#### 11 - 2. Testing Conditions and Inspection Criteria

For the final test the testing sample must be stored at room temperature for 24 hours, after the tests listed in Table 11-1, Standard specifications for Reliability have been executed in order to ensure stability.

No	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

#### 11-3. MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature $(25\pm5^{\circ}C)$ , normal humidity $(50\pm10\%$ RH), and in area not exposed to direct sun light.
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#### **12. Specification of Quality Assurance:**

12-1. Purpose

This standard for Quality Assurance should affirm the quality of LCD module products to supply to purchaser by YEEBO CORPORATION (Supplier).

12-2. Standard for Quality Test

a. Inspection:

Before delivering, the supplier should take the following tests, and affirm the quality of luct.

- product.
  - b. Electro-Optical Characteristics:

According to the individual specification to test the product.

- c. Test of Appearance Characteristics: According to the individual specification to test the product.
- d. Test of Reliability Characteristics:

According to the definition of reliability on the specification for testing products.

- e. Delivery Test:
  - Before delivering, the supplier should take the delivery test.
  - (i) Test method: According to ISO2859-1. General Inspection Level II take a single time.
  - (ii) The defects classify of AQL as following:

Major defect: AQL = 0.65Minor defect: AQL = 2.5

- Total defects: AQL = 2.5
- 12-3. Non- conforming Analysis & Deal With Manners
  - a. Non- conforming Analysis:
    - (i) Purchaser should supply the detail data of non- conforming sample and the non-conforming.
    - (ii) After accepting the detail data from purchaser, the analysis of non- conforming should be finished in two weeks.
  - (iii) If supplier can not finish analysis on time, must announce purchaser before 3 days.
  - b. Disposition of non- conforming:
    - (i) If find any product defect of supplier during assembly time, supplier must change the good product for every defect after recognition.
    - (ii) Both supplier and customer should analyze the reason and discuss the disposition of non- conforming when the reason of nonconforming is not sure.

#### 12-4. Agreement items

Both sides should discuss together when the following problems happen.

- a. There is any problem of standard of quality assurance, and both sides should think that must be modified.
- b. There is any argument item which does not record in the standard of quality assurance.
- c. Any other special problem.



12-5. Standard of The Product Appearance Test

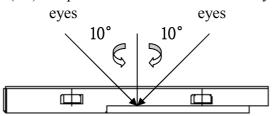
a. Manner of appearance test:

(i) The test must be under 20W  $\times$  2 or 40W fluorescent light, and the distance of view must be at 30±5cm.

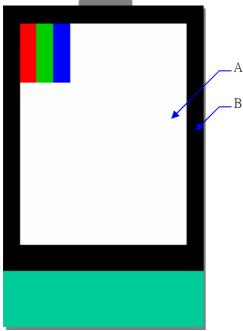
(ii) When test the model of transmissive product must add the reflective plate.

(iii)The test direction is base on around  $10^{\circ}$  of vertical line.

(iiii)Temperature: 25±5°C Humidity: 60±10%RH



(iv) Definition of area:



- A. Area: Viewing area.
- B. Area: Out of viewing area.

(Outside viewing area)

b. Basic principle:

- (i) It will accord to the AQL when the standard can not be described.
- (ii) The sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.
- (iii) Must add new item on time when it is necessary.
- c. Standard of inspection: (Unit: mm)



12-6. Inspection specification

Defect out of viewing area can be neglected.

NO	Item	Criterion				AQL
01	Electrical Testing	<ol> <li>1.1 Missing vertical, horizontal segment, segment contrast defect.</li> <li>1.2 Missing character, dot or icon.</li> <li>1.3 Display malfunction.</li> <li>1.4 No function or no display.</li> <li>1.5 Current consumption exceeds product specifications.</li> <li>1.6 LCD viewing angle defect.</li> <li>1.7 Mixed product types.</li> <li>1.8 Flicker</li> </ol>				
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	2.1 White and black or color spots on display $\leq 0.25$ mm, no more than Five spots. 2.2 Densely spaced: No more than three spots within 3mm.				
03	LCD and Touch Panel black spots, white spots, contamination (non – display)	3.1 Round type: As $x = (X+Y)/2$ $\downarrow \qquad \downarrow \qquad$	ensely spaced:	Size(mm) $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi \le 0.30$ $0.30 < \Phi$ No more than two ing)	Acceptable Q'ty Accept no dense 2 2 1 0 o spots within 3mm. Acceptable Q'ty Accept no dense 2 2 2 1 0	2.5
		L		0.15 <w< td=""><td>Rejection o lines within 3mm.</td><td></td></w<>	Rejection o lines within 3mm.	
			J~r			I



NO	Item	Criterion		
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in 	2.5	
05	Scratches	Follow NO.3 -2 Line Type.		
06	Chipped glass	Symbols: x: Chip length y: Chip width t: Glass thickness 	2.5	



NO	Item	Criterion				
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad:				
		y: Chip width x: Chip length z: Chip thickness				
		$y \leq 0.5 mm$ $x \leq 1/8a$ $0 < z \leq t$				
07	Glass crack	Non-conductive portion: y y x x x x x x x x	2.5			
		y: Chip width x: Chip length z: Chip thickness				
		$y \le L$ $x \le 1/8a$ $0 < z \le t$				
		<ul> <li>⊙ If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.</li> <li>⊙ If the product will be heat sealed by the customer, the alignment mark must mot be damaged.</li> <li>7.2.3 Substrate protuberance and internal crack</li> </ul> Y width x: length <ul> <li>y ≤ 1/3L</li> <li>X ≤ a</li> </ul>				



NO	Item	Criterion	AQL
08	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
09	Backlight elements	<ul> <li>9.1 Illumination source flickers when lit.</li> <li>9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards.</li> <li>9.3 Backlight doesn't light or color is wrong.</li> </ul>	2.5 2.5 0.65
10	Bezel	Bezel must comply with product specifications.	2.5
11	РСВ、СОВ	<ul> <li>11.1 COB seal may not have pinholes larger than 0.2mm or contamination.</li> <li>11.2 COB seal surface may not have pinholes through to the IC.</li> <li>11.3 The height of the COB should not exceed the height indicated in the assembly diagram.</li> <li>11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places.</li> <li>11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts.</li> <li>11.6 The jumper on the PCB should conform to the product characteristic chart.</li> </ul>	2.5 2.5 2.5 2.5 0.65 0.65
12	FPC	12.1 FPC terminal damage $\leq 1/2$ FPC terminal width and can not affect the function, we judge accept. 12.2 FPC alignment hole damage $\leq 1/2$ alignment area and can not affect the function, we judge accept.	2.5 2.5
13	Soldering	<ul><li>13.1 No cold solder joints, missing solder connections, oxidation or icicle.</li><li>13.2 No short circuits in components on PCB or FPC.</li></ul>	2.5 0.65



NO	Item	Criterion				AQL
14	Touch Panel Chipped glass	$z: Chip thickness$ $Z \leq t$ $\odot Unit: mm$	y: Chip width z: t: Touch Panel Total t gth hip: surface and crack betwo y: Chip width ≤ 1/2 k and not over viewing area	een panels: x: Chip length $x \le 1/8a$	side	2.5
		$z: Chip thickness$ $z \leq t$ $\odot Unit: mm$ $\odot If there are 2 or m$	y: Chip width $\leq 1/2$ k and not over viewing area hore chips, x is the total 1	x: Chip length x≦1/8a length of each chip		



NO	Item	Criterion	AQL	
15	Touch Panel(Fish eye, dent and bubble on film)	SIZE(mm)Acceptable Q'ty $\Phi \leq 0.2$ Accept no dense $0.2 < D \leq 0.4$ 5 $0.4 < D \leq 0.5$ 2 $0.5 < D$ 0	2.5	
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion( $\leq 2.5\%$ ), it is acceptable.		
17	Touch Panel Linearity	Less than 2.5% is acceptable.	2.5	
18	LCD Ripple	Touch the touch panel, can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	2.5	
19	General appearance	<ul> <li>19.1 Pin type must match type in specification sheet.</li> <li>19.2 LCD pin loose or missing pins.</li> <li>19.3 Product packaging must the same as specified on packaging specification sheet.</li> <li>19.4 Product dimension and structure must conform to product specification sheet.</li> </ul>	0.65 0.65 0.65 0.65	



#### **13. Handling Precaution:**

13-1 Handling of LCM

- Don't give external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance. Must not lick and swallow. when the liquid is attach to your hand, skin, cloth etc. Wash it out thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

#### 13-2 Storage

- Store in an ambient temperature of 25±10°C, and in a relative humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.
- Storage in a clean environment, free from dust, active gas, and solvent.
- Store in anti-static electricity container.
- Store without any physical load.

#### 13-3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: No higher than  $280\pm10^{\circ}$ C and less than 3 sec during Hand soldering.
- Rewiring: no more than 2 times.

#### 14. Guarantee:

Our products meet requirements of the environment.

YEEBO ROHS requirement is based on European Union Directive 2011/65/EU (ROHS) Requirements and Update.